

Title (en)

MODULE ASSEMBLY HAVING PIVOTABLE SEMICONDUCTOR MODULES FOR A HEADLAMP

Title (de)

MODULBAUGRUPPE MIT VERSCHWENKBAREN HALBLEITERMODULEN FÜR EINEN SCHEINWERFER

Title (fr)

ENSEMBLE MODULAIRE COMPORTANT DES MODULES À SEMI-CONDUCTEUR PIVOTANTS POUR UN PHARE

Publication

**EP 2872821 B1 20200115 (DE)**

Application

**EP 13732540 A 20130629**

Priority

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- EP 2013063757 W 20130629

Abstract (en)

[origin: WO2014009185A1] The invention relates to a module assembly (1) for a headlamp, comprising at least one semiconductor light module (10), and a method for adjusting the semiconductor light module (10), which is accommodated on a support frame (11), wherein the semiconductor light module (10) comprises a heat sink (12) having at least one semiconductor light source (13) accommodated on the heat sink (12). According to the invention, the support frame (11) has at least one ball socket (14), in which the semiconductor light module (10) having the heat sink (12) sits such as to be pivotable about a ball socket center point (15) and in which ball socket the semiconductor light module can be pivoted.

IPC 8 full level

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Citation (examination)

- WO 2011032616 A1 20110324 - HIRSCHMANN GMBH [DE], et al
- JP 2005071786 A 20050317 - KOITO MFG CO LTD, et al

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DOCDB simple family (publication)

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